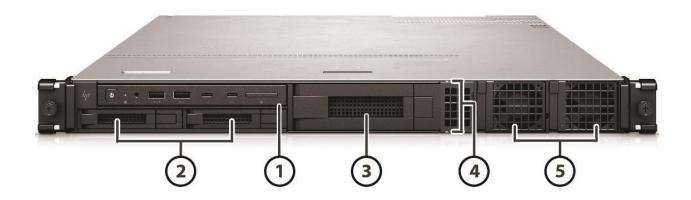
Overview

### **HP ZCentral 4R Workstation**



### Front view

- 1. Front I/O module options
  - Premium (optional shown here): power button, 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-C®, Headset audio, (Left-most Type-A port has charging capability), Smart Card not supported
  - Standard (optional): power button, 4 USB 3.1 G1 Type-A (left-most Type-A port has charging capability), Headset audio, Smart Card not supported
- 2. 2 x 2.5" external drive bays
- 3. 1 x 3.5" external drive bay (can be configured with 1 x 3.5" drive or 2 x 2.5" drives)
- 4. Locator LED
- 5. 2 x external 675W PSU bays

### **ENTRY**

Contains one (1) PSU 675W power supply.

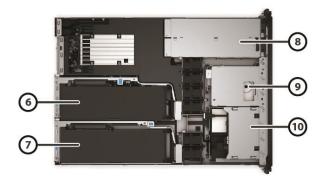
### **ENTRY REDUNDANT**

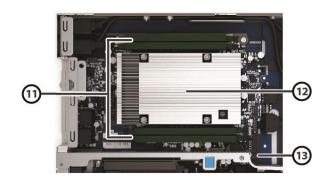
Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.

### **HIGH END**

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

### Overview



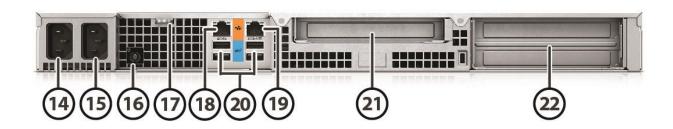


### **Internal views**

- Single Slot Riser (1 PCIe G3 x16); includes a single 6+2 auxiliary power cable
- 7. Dual Slot Riser\* (1 PCIe G3 x16; 1 PCIe G3 x16 wired as x8); includes an additional dual 6+2 auxiliary power cable
- 8. Power supply bays
- 9. 3.5" drive bay
- 10. Two 2.5" drive bays

- 11. Four DIMM slots; DDR4- 2933 ECC Reg RAM
- 12. Intel® Xeon® Processors: W-2200 family
- 13. Two PCIe G3 x4 M.2 for SSDs

\*Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary power cable



### **Rear view**

- 14. Primary power supply cable connector
- 15. Secondary power supply cable connector
- 16. Rear power button
- 17. Padlock loop
- 18. 1GbE RJ-45 (AMT)

- 19. 1/2.5/5/10GbE RJ-45
- 20. 4x USB 3.1 G1 Type-A
- 21. Single Slot Riser (1 PCIe G3 x16)
- 22. Dual Slot Riser\* (1 PCIe G3 x16; 1 PCIe G3 x16 wired as x8)



### Overview

\*Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary power cable

### **Overview**

### Form Factor Operating Systems

### 1U Rackable Workstation

#### Preinstalled:

- Windows 11 Pro for Workstations\*
- Windows 10 Pro for Workstations\*,\*\*
- Ubuntu Linux® 20.04\*\*\*
- HP Linux-ready (minimal OS ready for customer OS installation)\*\*\*\*

### Supported:

- Red Hat® Enterprise Linux® Desktop 7.4 (Paper license with 1 year support)
- Red Hat® Enterprise Linux® Desktop 8.0 (Paper license with 1 year support)
- Ubuntu 18.04 LTS
- Ubuntu 20.04 LTS

### **Supported Version:**

• HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282.

For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux\_hardware\_matrix

- \* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <a href="http://www.windows.com">http://www.windows.com</a>.
- \*\* Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
- \*\*\*Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.
- \*\*\*\*For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux\_hardware\_matrix.

**Note:** In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows® 7 operating system on products configured with Intel® and AMD 7th Generation and forward processors or provide any Windows® 8 or Windows® 7 drivers on http://www.support.hp.com

### **Supported Components**

### **Available Processors**

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	ECC memory support	Max memory support	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology 2.0 (GHz) <sup>1</sup>	Intel® Turbo Boost Max Technology 3.0 (GHz) <sup>1</sup>	TDP (W)
					Intel® Xe	on® W Proc	essors				
Intel® Xeon® W-2295 processor	18	3.0	24.75	2933	YES	512GB	YES	YES	3.8, 4.6	4.8	165
Intel® Xeon® W-2275 processor	14	3.3	19.25	2933	YES	512GB	YES	YES	4.1, 4.6	4.8	165
Intel® Xeon® W-2265 processor	12	3.5	19.25	2933	YES	512GB	YES	YES	4.3, 4.6	4.8	165
Intel® Xeon® W-2255 processor	10	3.7	19.25	2933	YES	512GB	YES	YES	4.3, 4.5	4.7	165
Intel® Xeon® W-2245 processor	8	3.9	16.5	2933	YES	512GB	YES	YES	4.5, 4.5	4.7	155
Intel® Xeon® W-2235 processor	6	3.8	8.25	2933	YES	512GB	YES	YES	4.3, 4.6	N/A	130
Intel® Xeon® W-2225 processor	4	4.1	8.25	2933	YES	512GB	YES	YES	4.5, 4.6	N/A	105
Intel® Xeon® W-2223 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120

<sup>1</sup>Intel Turbo Boost Max Technology 3.0 identifies the best performing core(s) on a processor and provides increased performance on those cores by taking advantage of power and thermal headroom. Intel® Turbo Boost Max Technology 3.0 frequency is the clock frequency of the CPU when running in this mode.

NOTE: Processors that do not have certain turbo functionality are denoted as N/A.

## Available Processors Disclaimers

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.



### Supported Components

**Expansion Slots** 

Slot 1 (SSR\*): PCI Express Gen3 x16 from CPU

(see system board section for more details)

Slot 2 (DSR\*): PCI Express Gen3 x16 from CPU - operates as x8 if Slot 3 is loaded

Slot 3 (DSR\*): PCI Express Gen3 x16 (wired as x8) from CPU

M.2 Slot 1: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-

Μ

M.2 Slot 2: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-M

\*SSR = Single slot riser. Includes single 6+2 pin auxiliary power cable

\*DSR = Dual slot riser. DSR is optional but required for double wide graphics cards and

configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary

power cable

**Expansion Bays** 

2 external 2.5" bays

(see storage section for more details)

(see storage section for more 1 external 3.5" bay (can be configured with 1 x 3.5" drive or 2 x 2.5" drives)

Front I/O

Base: Power button with power/fault LED, Drive activity LED,1 Headset audio port, 4

USB 3.1 G1 Type A (1 charging, provides 1.5A at 5V)

 Premium (optional): Power button with power/fault LED, Drive activity LED, 1 Headset audio port, 2 USB 3.1 G1 Type-A (1 charging, provides 1.5A at 5V), 2 USB 3.1 G2 Type-C<sup>®</sup>

(each provides 3A at 5V)

• SD Card Reader is not supported

Internal I/O

1 USB 2.0 dual-port header

**Rear I/O** 4x USB 3.1 G1 Type-A\*

1x 1/2.5/5/10GbE LAN port

1x 1GbE LAN port (supporting Intel AMT)

\*All rear I/O motherboard USB-A ports are 0.9A at 5V

**Interfaces Supported** 

4-channel SATA interface (6 @ 6.0 Gb/s)

USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (optional)

On-board RAID Support

SATA RAID 0 Striped Array Configuration SATA RAID 1 Mirrored Array Configuration SATA RAID 10 Striped/Mirrored Configuration

**Chassis Dimensions** 

Base footprint without front

bezel and rack brackets (H x W x D)

•

H: 1.685" (42.8mm)
W: 17.25" (438.15mm)
D: 24.61" (625mm)

D: 24.61" (625mm)

With front bezel and rack brackets (H x W x D)

H: 1.685" (42.8mm) W: 19.17" (486.81mm) D: 25.42" (645.70mm)

Packaged Dimensions H: 7.28" (185mm)

W: 23.22" (590mm) D: 32.48" (825mm)

**Palletization Profile** 

2 units per layer x 10 layers = 20 units per pallet

1200x1000x1980mm(included pallet)

Rack Dimensions 1U

Weight Exact weights depend upon configuration (System weight only).

Minimum: 10.7 kg (23.7 lbs.) Standard: 11.7 kg (25.9 lbs) Maximum: 13.6 kg (30 lbs)

Temperature

Non-operating: -40° to 60° C (-40° to 140° F)

Operating:  $5^{\circ}$  to  $35^{\circ}$  C ( $40^{\circ}$  to  $95^{\circ}$  F)



### Supported Components

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C

(1.8° F) for every 305 m (1.000 feet) increase in elevation

Maximum rate of change: 10 °C/hr No direct sustained sunlight

Operating: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb **Humidity** 

Non-operating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb

Maximum Altitude (nonpressurized)

**Power Supply** 

Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See Temperature for details.

The ZCentral 4R 675W power supply efficiency report can be found at this link:

https://clearesult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-

D9ayoBFKnzPUpASigKGy2B-My6Ng?e=cPfbnt

### **ENTRY**

Contains one (1) PSU 675W power supply.

### **ENTRY REDUNDANT**

Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.

NOTE: All power cords supplied by HP for Desktop Workstations are between 1.83m and 2.5m (dependent on country localization and platform)."

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

**Workstation ISV Certifications** See the latest list of certifications at

http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-Series CPU				
	Intel® Xeon® W-2295 3.0 2933 18C CPU	Υ	N		
	Intel® Xeon® W-2275 3.3 2933 14C CPU	Υ	N		
	Intel® Xeon® W-2265 3.5 2933 12C CPU	Υ	N		
	Intel® Xeon® W-2255 3.7 2933 10C CPU	Υ	N		
	Intel® Xeon® W-2245 3.9 2933 8C CPU	Υ	N		
	Intel® Xeon® W-2235 3.8 2933 6C CPU	Υ	N		
	Intel® Xeon® W-2225 4.1 2933 4C CPU	Υ	N		
	Intel® Xeon® W-2223 3.6 2933 4C CPU	Υ	N		

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.



### **Supported Components**

### Storage / Hard Drives\*

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations				
	1TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	WOR10AA	
	2TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	QB576AA	
	4TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	K4T76AA	

\*For storage drives, GB = 1 billion bytes. TB = one trillion bytes. Actual formatted capacity is less. Up to 35GB of disk space is reserved for system recovery software.

SATA Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Solid State Drives (SSDs) for Workstations				
	HP 256GB SATA SSD	Υ	Υ	A3D26AA	
	HP 512GB SATA SSD	Υ	Υ	D8F30AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	
	HP 2TB SATA SSD	N	Υ	Y6P08AA	
	HP 240GB SATA Ent SSD	Υ	Υ	T3U07AA	
	HP 480GB SATA Ent SSD	Υ	Υ	T3U08AA	
	HP 960GB SATA Ent SSD	Υ	Υ	1W6P8AA	
	HP 1920GB SATA Ent SSD	Υ	Υ	1W6P9AA	
	HP 512GB SATA SED OPAL2 SSD	N	Υ	N8T26AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	

PCIe Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Z Turbo Drive Dual Pro				
	HP Z Turbo Drive Dual Pro 512GB TLC SSD	Υ	Υ	4YF61AA	
	HP Z Turbo Drive Dual Pro 1TB TLC SSD	Υ	Υ	4YF62AA	
	HP Z Turbo Drive Dual Pro 2TB TLC SSD	Υ	Υ	4YF63AA	
	HP Z Turbo 256GB TLC 4R Kit SSD	Υ	Υ	2E3R0AA	
	HP Z Turbo 512GB TLC 4R Kit SSD	Υ	Υ	2E3R1AA	
	HP Z Turbo 1TB TLC 4R Kit SSD	Υ	Υ	2E3R2AA	
	HP Z Turbo 2TB TLC 4R Kit SSD	Υ	Υ	2E3R3AA	
	HP Z Turbo 512GB SED TLC 4R Kit SSD	Υ	Υ	2E3R4AA	
	HP Z Turbo 256GB SED TLC 4R Kit SSD	Υ	Υ	2E3R5AA	

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# QuickSpecs

### **Supported Components**

Intel® Virtual RAID on CPU (Intel® VROC) for NVMe	Factory	Option	Kit Part	Support
	Configured	Kit	Number	Notes
Intel® VROC NVMe SSD Standard Controller Module	N	Υ	3FJ80AA	1

**NOTE 1:** Enables RAID 0, 1 & 10

### **Graphics**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP miniDP-to-DP Adapter	Υ	Υ	2MY05AA	
HP miniDP-to-DP Adapter (12-pack)	Υ	N	2KW87A6	
Entry 3D				
NVIDIA® T400 2GB Graphics	Υ	Υ	340K8AA	2
NVIDIA® T400 4GB Graphics	Υ	Υ	5Z7EOAA/AT	2
Mid-range 3D				
NVIDIA® T1000 4GB Graphics	Υ	Υ	20X22AA/AT	2
NVIDIA® T1000 8GB Graphics	Υ	Υ	5Z7D8AA/AT	6
NVIDIA® RTX A2000 6GB Graphics	Υ	Υ	340L0AA	5
NVIDIA® RTX A2000 12GB Graphics	Υ	Υ	5Z7D9AA/AT	5
High-End 3D				
NVIDIA® Quadro® RTX 4000 8GB Graphics	Υ	Υ	5JV89AA	1
NVIDIA® RTX A4000 16GB Graphics	Υ	Υ	20X24AA/AT	1
NVIDIA® RTX A4500 20GB Graphics	Υ	Υ	5S458AA/AT	2
Ultra High-End 3D				
NVIDIA® Quadro® RTX 5000 16GB Graphics	Υ	Υ	5JH81AA	2,4
NVIDIA® RTX A5000 24GB Graphics	Υ	Υ	20X23AA	2
NVIDIA® RTX A6000 48GB Graphics	Υ	Υ	2S6U3AA/AT	2, 3

**NOTE 1:** Dual graphics configuration requires addition of Dual Slot Riser and High End Chassis with 1350W PSU; Single Slot Riser includes single 6+2 pin auxiliary power cable. Dual Slot riser includes an additional dual 6+2 pin auxiliary power cable.

**NOTE 2:** Dual Graphics not supported

**NOTE 3:** Single graphics configuration requires addition of Dual Slot Riser and High End Chassis with 1350W PSU. Dual Slot riser includes an additional dual 6+2 pin auxiliary power cable.

**NOTE 4:** The RTX 5000 can be configured with Redundant Power Supplies only when configured with processors with TDP ≤ 130W.

**NOTE 5:** The RTX A2000 does not support dual configurations. It requires the addition of the Dual Slot Riser. It is supported with the Entry Chassis, Entry Redundant Chassis, or the High End Chassis.

**NOTE 6**: A dual configuration of the T1000 8GB graphics card requires the Dual Slot Riser but does not require the High End chassis.

### **Supported Components**

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	8GB (1x8GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ56AA/AT	1
	16GB (1x16GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ54AA/AT	1
	32GB (1x32GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ55AA/AT	1
	64GB (1x64GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ57AA/AT	1
	Factory Configured System Memory Solutions				
	8GB (1x8GB) DDR4				
	16GB (1x16GB) DDR4				
	16GB (2x8GB) DDR4				
	24GB (3x8GB) DDR4				
	32GB (2x16GB) DDR4				
	32GB (4x8GB) DDR4				
	64GB (2x32GB) DDR4				
	64GB (4x16GB) DDR4				
	128GB (2x64GB) DDR4				
	128GB (4x32GB) DDR4				
	256GB (4x64GB) DDR4				

**NOTE 1:** ONLY DDR4 RDIMMs are supported.

**NOTE:** Factory-configured CTO (xxxxxAV) and aftermarket AMO (xxxxxAA, xxxxxAT) HP memory part numbers designated as "2933" will be transitioned to use "3200" speed memory components. This does not affect HP part number availability, nor does it affect system performance or operation. All hardware configurations currently supporting HP memory part numbers designated as "2933" have been tested to work with "3200" memory and are fully-supported by HP under standard support terms.

### **Multimedia and Audio Devices**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Realtek HD ALC3601 Audio	Υ	N		



### **Supported Components**

## **Networking and Communications**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Intel® Ethernet I219-LM Single Port 1Gb NIC	Υ	N		
Integrated Marvell® AQC-107 Single Port 1/2.5/5/10GbE				
NIC	Υ	N		
Intel® I210-T1 Single Port 1GbE	Υ	Υ	E0X95AA	
Intel® X550-T2 Dual Port 10GbE NIC	Υ	Υ	1QL46AA	
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Υ	Υ	1C7Q2AA	
NVIDIA® Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC	Υ	Υ	436M8AA	

## **Racking and Physical Security**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	
HP ZCentral 4R Front Bezel/Security	Υ	Υ	16G58AA		
HP ZCentral 4R Rail Rack Kit	Υ	Υ	16G60AA		
HP Rack Cable Management Arm	N	Υ	35Z34AA		

## **Input Devices**

	Factory	Option	Option Kit Part	Support
	Configured	Kit	Number	Notes
HP Wireless Business Slim Keyboard and Mouse	Υ	Υ	N3R88AA	
USB Business Slim Wired Keyboard	Υ	Υ	N3R87AA	
USB Premium Wired Keyboard	Υ	Υ	Z9N40AA	

### **Supported Components**

### Other Hardware

	Factory		Option Kit Part	Support
	Configured	Option Kit	Number	Notes
HP ENERGY STAR® Certified Configuration	Υ	N		
HP ZCentral 4R 2 <sup>nd</sup> 675W Power Supply	Υ	Υ	1C9J6AA	
HP ZCentral 4R Dual PCIe Slot Riser Kit	Υ	Υ	16G54AA	
HP ZCentral 4R Power Cord Kit	Υ	Υ	1N1D4AA	
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	Υ	Υ	16G59AA	
HP Serial Port and PS/2 Port	N	Υ	141K9AA	
HP Internal USB Port Kit		Υ	EM165AA	1
HP ZCentral 4R 2.5" Dual Drive Cage Adapter		Υ	16G55AA	
HP ZCentral 4R 2.5" Drive Carrier		Υ	16G56AA	
HP ZCentral 4R 3.5" Drive Carrier		Υ	16G57AA	
NOTES TO UNITED THE STATE OF TH	LICE S O L	A		

NOTE 1: The HP Internal USB Port Kit has a single USB 2.0 type A connector

# Application Software

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Sobey Video Editing SW	N	Υ		1
HP ZCentral Remote Boost	Υ	N		2
Data Science Stack	Υ	N		3,4
WSL2/Ubuntu Data Science Stack	Υ	N		3,5

\*Not all Application Software for Z Desktop Workstations is included with purchase.

NOTE 1: China Only

**NOTE 2:** HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase through 2022. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7.2 are only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

**NOTE 3:** Only available with NVIDIA graphics cards selections.

NOTE 4: Only available with Ubuntu 20.04 LTS preinstall.

**NOTE 5:** Only available with Windows 10 Pro/Pro for Workstations or Windows 11 Pro/Pro for Workstations.

### Software

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ZCentral Remote Boost	Υ	N		5
HP Sure Start Gen6	Υ	N		1
HP Sure Sense	Υ	N		2
HP Sure Click	Υ	N		
HP PC Hardware Diagnostics UEFI	Υ	N		
<b>HP PC Hardware Diagnostics Windows</b>	Υ	N		6
HP Performance Advisor	Υ	N		4
HP Client Security Manager Gen5	N	Υ		3
HP Manageability Integration Kit Gen4	N	Υ		5



### **Supported Components**

Sobey Video Editing SW

1

Support Notes

**NOTE 1:** HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

NOTE 2: HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A\_SureClick for complete details.

**NOTE 3:** HP Manageability Integration Kit can be downloaded from

http://www.hp.com/go/clientmanagement.

**NOTE 4:** HP Client Security Manager Gen5 requires Windows and is available on the select HP Elite and Pro PCs.

**NOTE 5:** HP Sure Start Gen6 is available on select HP PCs and requires Windows 10.

**NOTE 6:** HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html

### **Operating Systems**

	2nhhoir uore2
Windows 11 Pro for Workstations	1
Windows 10 Pro for Workstations	2
Red Hat® Enterprise Linux® Desktop 7.4	3, 4
Red Hat® Enterprise Linux® Desktop 8.0	3, 4
Ubuntu 18.04 LTS	4
Ubuntu 20.04 LTS	4

**NOTE 1:** Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See <a href="http://www.windows.com">http://www.windows.com</a>.

**NOTE 2:** Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

NOTE 3: Paper license with 1 year support

**NOTE 4:** For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux\_hardware\_matrix



### **System Technical Specifications**

### **System Board**

**System Board Form** 

**Factor** L-Shaped

11.71 x 12.15 inches Single LGA2066 R4

Processor Socket

Single LGAZU66 R4

Chipset

Intel® Xeon® W Processor Family

Intel® C422 Chipset

Super I/O Controller

Nuvoton NPCD315HA0DX (SIO-15)

**Memory Expansion** 

4 DDR4 memory slots

Slots

Memory Type

DDR4, RDIMM (Registered), ECC

Supported Memory Modes

Channel Interleaved

**Memory Speed** 

2933MT/s, 2666MT/s and 2400MT/s

Supported

**Memory Protection** ECC available on data, parity on address and command

Maximum Memory

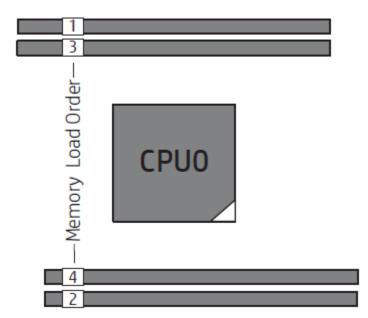
Supports up to 256GB

Memory Configuration

(Supported)

Only Registered DIMMs are supported.

### **Memory Load Order**



Note on Maximum Memory Maximum memory capacities assume 64-bit operating systems such as Windows 10 Pro 64-bit, Windows 7 Professional 64-bit.

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

### **System Technical Specifications**

**PCI Express Connectors Slot 1 (SSR\*):** PCI Express Gen3 x16 supplied by CPU

Slot 2 (DSR\*): PCI Express Gen3 x16 supplied by CPU (operates as x8 if Slot 3 is loaded)

**Slot 3 (DSR\*):** PCI Express Gen3 x16 (wired as x8) supplied by CPU

M.2 Slot 1: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, 2280-D5-M, 22110-D5-M

M.2 Slot 2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, 2280-D5-M, 22110-D5-M

\*SSR = Single slot riser. Includes single 6+2 pin auxiliary power cable

\*DSR = Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary

power cable

**Supported Drive Interfaces** 

SATA

4 SATA @ 6GB/s, supports RAID 0,1, and 10

Factory integrated Intel® SATA RAID is Microsoft Windows only

Serial Attached SCSI Not supported

**Factory Configured RAID** 

RAID 0 striped array

RAID 1 mirrored array

RAID 10 striped and mirrored array

\*HW RAID functionality not supported by Linux®. Use SW RAID functionality provided in the Red Hat®

Operating system instead.

Integrated Graphics No

**Network Controller** M

Marvell AQtion AQC107 PCIe 1/2.5/5/10GBASE-T LAN

Intel® I219-LM PCIe GbE LAN supports the following management functionalities: Intel AMT11.12,

TXT, DASH 1.1, WOL, VLAN, Teaming and PXE 2.1

External SATA (eSATA) No

**IDE connector** No

Floppy connector No

Serial and PS2 1 internal header

2nd SerialNoParallelNoAUX IN (audio)NoIEEE 1394 Connector(s)No

**USB Connector(s)** 

**Front** Front USB depends on which FIO module is selected:

- Standard: 4 USB 3.1 G1 Type A (1 charging)

- Premium: 2 USB 3.1 G2 Type C<sup>®</sup>, 2 USB 3.1 G1 Type A (1 charging)

Rear 4 USB 3.1 G1 Type A

1 USB 2.0 single-port header 1x USB 2.0 dual-port header

**HD Integrated Audio** 

Realtek ALC3601-CG

Flash ROM

Yes



### **System Technical Specifications**

**Fan Headers** Yes Front Control Panel/Speaker Yes

Header

CMOS Battery Holder -Yes

Lithium

Integrated Trusted Platform Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Module Common Criteria EAL4+ Certified

Yes

Yes

Convertible to FIPS 140-2 Certified mode through firmware v7.85

TPM Certified products list:

https://trustedcomputinggroup.org/membership/certification/tpm-certified-products/

**Power Supply Headers** Power Switch, Power LED & **Hard Drive LED Header** 

**Clear Password Jumper** Yes

1 internal header **Serial Port** 

**Parallel Port** 

**Keyboard/Mouse** USB (PS/2 supported via AMO kit)

**Hood Lock Header** No **Hood Sensor Header** Yes

**AUX OUT (audio)** (Front Audio) Headset



### System Technical Specifications

**Power Supply** 

The HP ZCentral 4R Workstation contains up to two (2) 675 watt wide-ranging, active Power Factor Correction, 90% Efficient PSUs.

The 675W power supply efficiency report can be found at this link:

https://clearesult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-D9ayoBFKnzPUpASiqKGy2B-My6Ng?e=cPfbnt

**ENTRY** 

Contains one (1) PSU 675W power supply.

**ENTRY REDUNDANT** 

Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.

**HIGH END** 

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

Power Supply 675W 90% Efficient, Custom PSU (Wide-Ranging, Active PFC)

Operating Voltage Range 90–269 VAC

 Rated Voltage Range
 100-240 VAC
 118 VAC

 Rated Line Frequency
 50-60 Hz
 400 Hz

 Operating Line Frequency
 47-66 Hz
 393-407 Hz

Range 47-66 HZ 393-407 HZ

**Rated Input Current**9A @100-127 VAC

4.5A @ 200-240 VAC

7A @ 118VAC

**Heat Dissipation**(Configuration and software dependent)

Typical = 1832 btu/hr

Max = 2647 btu/hr

Power Supply Fan 40x40 mm variable speed

ENERGY STAR® Certified
(Configuration dependent)

90% Efficient
The power supply efficiency report can be found at this link:

80 PLUS® Compliant https://clearesult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-D9ayoBFKnzPUpASiqKGy2B-

My6Nq?e=cPfbnt

FEMP Standby Power
Compliant @115V Yes, 1 PSU only Yes, 1 PSU only

<1W in S5 – Power Off)

EuP Compliant @ 230V

N/A for EMC Class A Equipment

N/A for EMC Class A Equipment

(<0.5 W in S5 – Power Off)

NATOLEMC Class A Equipment
NATOLEMC Class A Equipment
NATOLEMC Class A Equipment

mode
(as defined by ENERGY <10W <10

STAR®) – Suspend to RAM
(S3)

(Instantly Available PC)

Built-in Self Test LED

No
No

**System Technical Specifications** 

Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)

Yes

Yes



## **System Technical Specifications**

## **System Configuration**

Example ZCentral 4R	Processor	Intel Xeon W-	2223 4C 3.6GH	Z				
Workstation	Memory	1x 8GB DDR4	2933 (Register	ed DIMM)	d DIMM)			
Configuration #1	Graphics	1x NVIDIA Qua	adro P400					
ENERGY STAR®	Disks / Optical	1x HP Zturbo	M.2 512GB TLC	SSD				
Certified	Power Supply	1x 675W						
	Other	N/A						
		115	5 VAC	230	VAC	100	VAC	
Energy Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	45	.219	45.	379	45.	143	
	Windows Busy Typ(S0)	144	1.871	142	142.362		140.95	
	Windows Busy Max (S0)	150	0.762	149.580		148.992		
	Sleep (S3)	5.540	5.321	5.548	5.322	5.535	5.322	
	Off (S5)	2.945	2.524	3.13	3.005	3.112	2.998	
	Zero Power Mode (ErP)	0.	300	0.314		0.301		
		115	5 VAC	230	230 VAC		100 VAC	
<b>Heat Dissipation</b>		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	154.287		154	.833	154.027		
	Windows Busy Typ(S0)	494.299		485	.732	480	0.92	
	Windows Busy Max (S0)	514.399		510	.366	508	3.36	
	Sleep (S3)	18.902	18.902 18.155		18.129	18.885	18.158	
	Off (S5)	10.631	10.239	10.679	10.653	10.618	10.229	
	Zero Power Mode (ErP)	1.	023	1.071		1.0	)27	



## **System Technical Specifications**

Example ZCentral 4R	Processor	1x Intel Xeon	W-2245 8C 3.9	GHz					
Workstation	Memory	2x16GB DDR4	1-2933 (Registe	red DIMM)	red DIMM)				
Configuration #2	Graphics	1x NVIDIA Qua	adro P2200						
ENERGY STAR®	Disks / Optical	1x ZTurbo 25	6GB M.2 SSD; 1	x 2TB 7200 S	ATA Enterprise	3.5in HDD			
Certified	Power Supply	1x 675W							
	Other	N/A							
Energy Consumption		115	5 VAC	230	VAC	100	VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	53.157		53.	368	52.	983		
	Windows Busy Typ(S0)	272.91		270	0.65	267.35			
	Windows Busy Max (S0)	27	9.43	280.36		279.37			
	Sleep (S3)	5.314	5.375	5.328	5.371	5.321	5.381		
	Off (S5)	2.945	2.908	2.943	2.9	2.963	2.902		
	Zero Power Mode (ErP)	0.	301	0.312		0.303			
		11!	5 VAC	230	VAC	100 VAC			
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled		
(Btu/hr)	Windows Idle (S0)	181.371 931.168 953.415		182	.091	184.374			
	Windows Busy Typ(S0)			923	.457	912	.198		
	Windows Busy Max (S0)			956.58		953.21			
	Sleep (S3)	18.131	18.339	18.179	18.325	18.155	18.359		
	Off (S5)	10.048	9.922	10.041	9.894	10.017	9.901		
	Zero Power Mode (ErP)	1.	027	1.065		1.034			



## **System Technical Specifications**

Example ZCentral 4R	Processor	1x Intel Xeon	W-2255 10C 3.	'GHz				
Workstation	Memory	4x 16GB DDR	4-2933 (Regist	ered DIMM)	red DIMM)			
Configuration #3	Graphics	1x NVIDIA Qua	adro RTX4000					
	Disks/Optical	1x Zturbo 512	2GB M.2 SSD; 1	k 4TB 7200 En	terprise SATA	HDD		
	Power Supply	1x 675W						
	Other	N/A						
Energy Consumption		115	5 VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	56.77		57.	035	56.	763	
	Windows Busy Typ(S0)	335.24		333	333.25		330.97	
	Windows Busy Max (S0)	34	5.36	344.89		344.67		
	Sleep (S3)	5.883	5.829	5.883	5.842	5.88	5.835	
	Off (S5)	2.949	2.915	2.948	2.918	2.945	2.912	
	Zero Power Mode (ErP)	0.	303	0.316		0.306		
		115	5 VAC	230 VAC		100 VAC		
<b>Heat Dissipation</b>		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	193.699 1143.839		194	.603	193.583		
	Windows Busy Typ(S0)			1137	7.049	1129.27		
	Windows Busy Max (S0)	1178.36		1176.76		1176.01		
	Sleep (S3)	20.072	19.888	20.072	19.932	20.062	20.072	
	Off (S5)	10.061	9.945	10.058	9.956	10.048	10.061	
	Zero Power Mode (ErP)	1.	034	1.078		1.044		



### **System Technical Specifications**

Example ZCentral 4R	Processor	1x Intel Xeon	W-2295 18C 3	.0GHz				
Workstation	Memory	4x 32GB DDR4	1-2933 (Regis	itered DIMM)				
Configuration #4	Graphics	1x NVIDIA RTX	1x NVIDIA RTX8000					
	Disks / Optical	2x ZTurbo 2TE	3 M.2 SSD; 2x	ZTurbo 2TB Z	Dual Pro PCIe	SSD; 4x 1TB 2.	5in SATA SSD	
	Power Supply	2x 675W PSU						
	Other	N/A						
<b>Energy Consumption</b>		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	60.489		60.	889	60.413		
	Windows Busy Typ(S0)	464.	213	458	.512	461. 441		
	Windows Busy Max (S0)	495.	789	487.213		491.220		
	Sleep (S3)	5.893	5.819	5.990	5.831	5.887	5.412	
	Off (S5)	3.312	3.012	3.418	3.111	3.303	3.045	
	Zero Power Mode (ErP)	0.523		0.774		0.517		
		115	VAC	230	230 VAC		100 VAC	
<b>Heat Dissipation</b>		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	206.	388	207	207.753		206.129	
Windows Busy Typ(S0)		1583	.894	1563	1563.984		1574.4367	
	Windows Busy Max (S0)	1691.632		1662	2.370	1676	5.043	
	Sleep (S3)	20.107	19.854	20.437	19.895	20.086	18.465	
	Off (S5)	11.301	10.277	11.662	10.615	11.269	10.389	
	Zero Power Mode (ErP)	1.78	344	2.6	411	1.7641		

**NOTE:** Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

**System Technical Specifications** 

### **DECLARED NOISE EMISSIONS**

<b>Declared Noise Emissions</b>	(Entry-level and High-end	configurations)					
System Configuration Processor Info		Intel® Xeon® W-2255 3.	7GHz 2933MHz 10C CPU				
(Entry level)	Memory Info	256GB (4x64GB) DDR4-2933 ECC Reg RAM					
	Graphics Info	1-NVIDIA® Quadro® RTX 4000					
	Disks/Optical	1-4TB SATA 7200RPM 3.5" HDD / 2-	-1TB 2.5" SSD / 2-2TB PCle M.2 SSD				
	Power Supply	Single 675W					
<b>Declared Noise Emissions</b> (in accordance with ISO		Sound Power (LWAd, bels)	<b>Deskside Sound Pressure</b> (LpAm, decibels)				
7779 and ISO 9296)	Idle	4.9	34				
	Hard drive Operating (random reads)	4.9	34				

**NOTE:** Higher noise levels may be experienced with non-HP approved graphic card(s). Some consumer graphics cards have side blowing fans that may heat up thermal sensor(s) on the mother board causing fans to ramp.



### System Technical Specifications

### **ENVIRONMENTAL DATA**

**Environmental** Requirements

**Temperature** Non-operating: -40° to 60° C (-40° to 140° F)

Operating: 5° to 35° C (40° to 95° F)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1°C (1.8°F) for every 305 m (1,000 feet) increase in elevation

Maximum rate of change: 10 °C/hr No direct sustained sunlight

**Humidity** Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

**Maximum Altitude** Operating (with Rotational Hard Drives): 3.048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

Shock (non-repetitive) Operating: 1/2-sine: 40q, 2-3ms (~62 cm/sec)

Non-operating:  $\frac{1}{2}$ -sine: 160 cm/s, 2-3ms (~105g)

Non-operating square: 422 cm/s, 20g

**Vibration** Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g<sup>2</sup>/Hz

Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g<sup>2</sup>/Hz

### **Physical Security and Serviceability**

**Access Panel** Tool-less

Includes system board and memory information.

**Hard Drives** Screw-mounted

**Expansion Cards** Expansion card cage removal/insertion into system is tool-less

Expansion card access requires removal of screw-mounted retainer bracket

**Processor Socket** Tool-less

**Blue User Touch Points** Yes, on primary serviceable components.

Color-coordinated Cables Yes

and Connectors

**Memory DIMM Connectors Tool-less System Board** Screw-mounted

**Dual Color Power/Failure** Yes

LED

**HDD Activity LED** Yes

Note: HDD Activity LED is not dual-color

**Configuration Record SW** 

Restore CD/DVD Set

**Over-Temp Warning on** Yes, at POST screen on reboot

Screen

Restores the computer to its original factory shipping image; can be obtained via HP Support.

Yes, causes a fail-safe power off when held for 4 seconds **Dual Function Front** 

**Power Switch** 

**Padlock Support** Yes (optional): Locks top cover and secures chassis from theft 7.0 mm (0.2756 in) diameter padlock loop at rear of system

**Cable Lock Support** Yes. Kensington Cable Lock (optional): Secures chassis from theft

3 mm x 7 mm slot at rear of system

### System Technical Specifications

**Universal Chassis Clamp** No

**Lock Support** 

**Chassis Interlock Sensor** Yes

Sensor detects when the access panel has been removed. The access panel must be installed for the

system to power ON.

Serial, USB, Audio,

Network. Enable/Disable

**Port Control** 

Yes, enables or disables serial, USB, audio, and network ports

Removable Media Write/Boot Control Yes, prevents ability to boot from removable media on supported devices (and can disable writes to media)

Power-On Password

Yes, prevents an unauthorized person from booting up the workstation

**Setup Password** 

Yes, prevents an unauthorized person from changing the workstation configuration

3.3V Aux Power LED on

**System PCA** 

Yes

NIC LEDs (integrated)

Yes

(Green & Amber) **CPUs and Heatsinks** 

A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Power Supply Diagnostic Yes

**LED** 

Solid Green (OK); Blinking Green (Standby); Red (Fault); Off (No AC Power/PSU Failure)

**Front Power Button** Yes, ACPI multi-function

**Rear Power Button** Yes System Locator LED Yes, blue

**Front Power LED** Yes, white (normal), red (fault)

Front Hard Drive Activity Yes, white

LED

Yes

Flash Recovery

Internal Speaker

**System/Emergency ROM** Recovers corrupted system BIOS.

**Cooling Solutions** Air cooled forced convection heatsinks **Power Supply Fan** 40 mm x 40 mm x 28 mm (non-serviceable) 40 mm x 40 mm x 56 mm (serviceable) **Chassis Fans** 

**HP PC Hardware Diagnostics UEFI**  HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot and is available as a download from HP Support.

**Access Panel Key Lock** 

**ACPI-Ready Hardware** 

Advanced Configuration and Power Management Interface (ACPI).

Allows the system to wake from a low-power mode.

Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Infineon TPM 2.0 Certified

Chip

Integrated Chassis

Handles

No

**Power Supply** Tool-less

**PCIe Card Retention** Yes, rear (all), middle (all), front (full-length cards with extender)

Flash ROM Yes **Diagnostic Power Switch** Yes

**LED** on board

### System Technical Specifications

**Clear Password Jumper** Yes **Clear CMOS Button** Yes **CMOS Battery Holder** Yes

BIOS

**BIOS 32-bit Services** 

Standard BIOS 32-bit Service Directory Proposal v0.4

PCI 3.0 Support

Full BIOS support for PCI Express through industry standard interfaces.

**ATAPI BBS** 

ATAPI Removable Media Device BIOS Specification Version 1.0. BIOS Boot Specification v1.01.

**WMI Support** 

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

**BIOS Power On ROM Based Computer**  Users can define a specific date and time for the system to power on.

Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Recovers system BIOS in corrupted Flash ROM.

Flash Recovery with Video

**Replicated Setup** 

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigUtility.exe

utility can then replicate these settings on machines being deployed without entering Computer

Configuration Utility (F10 Setup).

**SMBIOS Boot Control**  System Management BIOS 3.2, for system management information. Disables the ability to boot from removable media on supported devices.

**Memory Change Alert Thermal Alert** 

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

• ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash

Provides secure, fail-safe ROM image management from a central network console.

ACPI (Advanced

Allows the system to enter and resume from low power modes (sleep states).

**Configuration and Power** Management Interface)

Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 5.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

**Remote Wakeup/Remote** System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC

Allows for very low power consumption with quick resume time.

(Suspend to RAM - ACPI sleep state \$3)

**Remote System** 

Installation via F12 (PXE 2.1) (Remote Boot from

Allows a new or existing system to boot over the network and download software, including the operating system.

Server)

**ROM revision levels** 

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

### System Technical Specifications

**System board revision** Allows management SW to read revision level of the system board.

**level** Revision level is digitally encoded into the HW and cannot be modified.

Start-up Diagnostics (Power-on Self-Test) Assesses system health at boot time with selectable levels of testing.

Auto Setup when new hardware installed

System automatically detects addition of new hardware.

**Keyboard-less Operation** The system can be booted without a keyboard.

**Localized ROM Setup** Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with

local keyboard mappings.

**Asset Tag** The user or MIS to set a unique tag string in non-volatile memory.

Revision Supported by the BIOS

Per-slot Control Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.

Adaptive Cooling Control parameters are set according to detected hardware configuration for optimal acoustics.

Pre-boot Diagnostics (Pre-video) critical errors are reported via beeps and blinks on the power LED.

Pre-boot Diagnostics Industry Standard Specification Support Industry Standard

UEFI Specification

2.6

Revision

**PMM** 

ACPI Advanced Configuration and Power Management Interface, Version 5.0
ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot "El Torito" Bootable CD-ROM Format Specification Version 1.0

**EDD** - Enhanced Disk Drive Specification Version 1.1

- BIOS Enhanced Disk Drive Specification Version 3.0

**EHCI** Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3

PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 2.0

PCI Express PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0

POST Memory Manager Specification, Version 1.01

SATA Serial ATA Specification, Revision 1.0a

Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified

FIPS 140-2 Certified

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

**UHCI** Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 G1 Specification Universal Serial Bus Revision 3.1 G2 Specification

SMBIOS System Management BIOS Reference Specification, Version 3.2

### System Technical Specifications

### Social and Environmental Responsibility

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be **Declarations** labeled with one or more of these marks:

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program (CECP)
- The ECO declaration (TED)
- The ZCentral 4R is registered EPEAT® Gold in the US and Canada. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

### **Batteries**

The battery in this product complies with EU Directive 2006/66/EC

Battery mass: 3a

Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

**Restricted Material Usage** This product meets the material restrictions specified in HP's General Specification for the Environment. HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. This product contains low halogen printed circuit boards.

### Low Halogen Statement

(Note: optional low halogen power cables are available for some countries in Europe)

## and Recycling

**End-of-Life Management** HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

### **HP Inc. Corporate Environmental** Information

For more information about HP's commitment to the environment:

Sustainable Impact Report

Eco-label certifications ISO 14001 certificates

### **Additional Information**

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. Product Disassembly Instructions
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and IS01043.

### **Packaging**

HP Workstation product packaging meets the HP's General Specification for the Environment

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency



### **System Technical Specifications**

- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting
- A multi-unit eco packaging option is available to institutional customers that uses less packaging material or has a lower volume footprint than conventional single-unit packaging. Please contact your sales representative for additional details.

Packaging Materials Internal External

Cushions and plastic bags made of low density polyethylene (LDPE). Outer carton, accessories carton, and insert made of corrugated paper board.



### System Technical Specifications

### Manageability

### **Industry Standard Specifications**

This product meets the following industry standard specifications for manageability functionality:

DASH 1.1 (via Intel® LAN on motherboard)

## Technology (AMT)

Intel Active Management Intel® Active Management Technology (AMT) 11.12

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.12 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
  - Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- NEW: Hardware Alerting (with special enablement for RPSU alerting)
- **Agent Presence**
- **System Defense Filters**
- Serial Over LAN (SOL)
- **USB Redirect (Media Redirection)**
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- **IPv6** Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC

Remote Memory Dump Command – Creates memory dump for debug

**Intel® vPro™ Technology** The HP ZCentral 4R Workstation supports Intel® vPro™ technology when configured as outlined below:

- Intel® Xeon® processor W-2200 product family featuring Intel® vPro™ Technology
- Intel® C422 chipset

### Intel® I219LM GbE LAN

### **Remote Manageability Software Solutions**

The HP ZCentral 4R Workstation is supported on the following optional remote manageability software consoles:

- **HP ZCentral Connect**
- Ivanti Management Suite
- Microsoft System Center Configuration Manager

For questions or support for manageability needs, please visit

http://www.hp.com/go/easydeploy



### **System Technical Specifications**

### System Software Manager

For easy deploy questions or support for SSM, please visit: http://www.hp.com/go/ssm

## Service, Support, and Warranty

On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

**NOTE 1:** Terms and conditions may vary by country. Certain restrictions and exclusions apply. **NOTE 2:** On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

**NOTE 3:** Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

### Product Change Notification

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.

### Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors Intel® Xeon® W-2223 3.6 2666 4C CPU

Intel® Xeon® W-2225 4.1 2933 4C CPU Intel® Xeon® W-2245 3.9 2933 8C CPU

Hard Drives 1TB SATA 7200RPM Ent 3.5" HDD

1TB HP Z Turbo M.2 TLC 4R Kit SSD

Graphics N/A

### **Technical Specifications - Processors**

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	ECC memory support	Max memory support	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology 2.0 (GHz) <sup>1</sup>	Intel® Turbo Boost Max Technology 3.0 (GHz) <sup>1</sup>	TDP (W)
					Intel® Xe	on® W Proc	essors				
Intel® Xeon® W-2295 processor	18	3.0	24.75	2933	YES	512GB	YES	YES	3.8, 4.6	4.8	165
Intel® Xeon® W-2275 processor	14	3.3	19.25	2933	YES	512GB	YES	YES	4.1, 4.6	4.8	165
Intel® Xeon® W-2265 processor	12	3.5	19.25	2933	YES	512GB	YES	YES	4.3, 4.6	4.8	165
Intel® Xeon® W-2255 processor	10	3.7	19.25	2933	YES	512GB	YES	YES	4.3, 4.5	4.7	165
Intel® Xeon® W-2245 processor	8	3.9	16.5	2933	YES	512GB	YES	YES	4.5, 4.5	4.7	155
Intel® Xeon® W-2235 processor	6	3.8	8.25	2933	YES	512GB	YES	YES	4.3, 4.6	N/A	130
Intel® Xeon® W-2225 processor	4	4.1	8.25	2933	YES	512GB	YES	YES	4.5, 4.6	N/A	105
Intel® Xeon® W-2223 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120

<sup>1</sup>Intel Turbo Boost Max Technology 3.0 identifies the best performing core(s) on a processor and provides increased performance on those cores by taking advantage of power and thermal headroom. Intel® Turbo Boost Max Technology 3.0 frequency is the clock frequency of the CPU when running in this mode.

**NOTE:** Processors that do not have certain turbo functionality are denoted as N/A.



0.32ms\*

7.45ms\*

14.2ms\*

**Technical Specifications - Hard Drives** 

### STORAGE/HARD DRIVES

**SATA Hard Drives for HP Workstations**  1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 1TB **SATA Protocol** 3.5" **Form Factor** Controller **AHCI** 

Reliability (MTBF) 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365

operation Physical Size (Height) 1 in; 2.54 cm Physical Size (Width) 4 in; 10.17 cm **Media Diameter** 3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

YES

**Synchronous Transfer** 

Rate (Maximum)

128MB

Up to 600MB/s\*

**Buffer** Seek Time (typical reads, Single Track includes controller **Average** 

overhead, including settling)

**Operating Temperature** 41° to 140° F (5° to 60° C)

**Performance** Sequential Read up to 226MB/s\* **Sequential Write** up to 226MB/s\*

**Full Stroke** 

**Enterprise Class** High Reliability

**Features** 

\*Actual performance may vary.



### **Technical Specifications - Hard Drives**

2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity2TBProtocolSATAForm Factor3.5"ControllerAHCIReliability (MTBF)2.0M hoursRated Power On Hours8760/yrAnnualized Failure<0.62%</th>

Rate (based on Rated

POH)

Rated for 24/7/365 YES

operation

Physical Size (Height) 1 in; 2.54 cm Physical Size (Width) 4 in; 10.17 cm Media Diameter 3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s\*

Synchronous Transfer

Rate (Maximum)

Buffer 128MB

Seek Time (typical<br/>reads, includesSingle Track<br/>Average0.48ms\*controller overhead,<br/>including settling)Full Stroke14.2ms\*

Operating Temperature

Performance

41° to 140° F (5° to 60° C)

Sequential Read up to 226MB/s\* Sequential Write up to 226MB/s\* High Reliability

Enterprise Class

**Features** 

\*Actual performance may vary.

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) **Capacity** 4TB

**Height** 0.275 in; 0.7 cm

Width Media Diameter 2.5 in; 6.36 cm Physical Size 2.75 in; 6.99 cm

Interface Serial ATA (6Gb/s), NCQ enabled

**Synchronous Transfer** Up to 600MB/s\*

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads,<br/>includes controller<br/>overhead, including<br/>settling)Single Track<br/>Average<br/>Full Stroke0.7ms\*8.5ms\*<br/>9.57ms\*

**Rotational Speed** 7,200 rpm

**Operating Temperature** 32° to 140° F (0° to 60° C)

\*Actual performance may vary.

### **Technical Specifications - Hard Drives**

SATA	SSDs	for	HP
Work	statio	ns	

HP 256GB SATA 6Gb/s SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

**Endurance** 192TBW (TB Written)

**Reliability (MTTF)** 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s\*

Rate (Maximum)

**Operating Temperature** 

32° to 158° F (0° to 70° C)

**Performance** 

**Sequential Read** 530MB/s (max)\* **Sequential Write** 500MB/s (max)\* **Random Read** 55K IOPS (max)\* **Random Write** 83K IOPS (max)\*

### **HP 512GB SATA 6Gb/s** SSD

Capacity 512GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

388TBW (TB Written) **Endurance** 

**Reliability** (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s

**Synchronous Transfer** Rate (Maximum)

Up to 550MB/s (Sequential Read)\*

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance Sequential Read** 530 MB/s\*

**Sequential Write** 500 MB/s\* **Random Read** 95K IOPS\* **Random Write** 83K IOPS\*

<sup>\*</sup>Actual performance may vary.

<sup>\*</sup>Actual performance may vary.

### **Technical Specifications - Hard Drives**

<b>HP 1TB SATA</b>	6Gb/s SSD
--------------------	-----------

Capacity1TBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

**Endurance** 400TBW (TB Written)

Reliability (MTTF)1.5M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/s

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)\*

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 530 MB/s\*
Sequential Write 500 MB/s\*
Random Read 95K IOPS\*
Random Write 83K IOPS\*

### HP 1920GB SATA 6Gb/s SSD

Capacity 1920GB

Protocol SATA
Form Factor 2.5"
Controller AHCI
NAND Type 3D TLC

**Endurance** 4,400TBW (TB Written)

Reliability (MTTF) 2.0M hours
Physical Size (Height) 0.28 in; 0.7 cm
Physical Size (Width) 2.5 in; 6.36 cm
Interface SATA 6Gb/s

Synchronous Transfer Rate (Maximum)

Up to 600MB/s (Sequential Read)\*

**Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 5340MB/s\*

Sequential Write 460 MB/s\*
Random Read 93K IOPS\*
Random Write 74K IOPS\*

**Enterprise Class Features** High Endurance NAND

Power Loss Protection End-to-End Data Protection



<sup>\*</sup>Actual performance may vary.

<sup>\*</sup>Actual performance may vary.

### **Technical Specifications - Hard Drives**

<b>HP Enterprise Class</b>
240GB SATA SSD

Capacity 240GB **Protocol SATA Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

**Endurance** 2,190TBW (TB Written)

**Reliability** (MTTF) 2.0M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in: 6.36 cm Interface 6Gb/s SATA **Synchronous Transfer** Up to 600MB/s\*

Rate (Maximum)

**Performance** 

**Operating Temperature** 32° to 158° F (0° to 70° C)

> **Sequential Read** 540 MB/s\* **Sequential Write** 310 MB/s\* **Random Read** 93K IOPS\* **Random Write** 48K IOPS\*

**Enterprise Class Features** High Endurance NAND

**Power Loss Protection End-to-End Data Protection** 

#### **HP Enterprise Class 480GB SATA SSD**

Capacity 480GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

4,380TBW (TB Written) **Endurance** 

**Reliability** (MTTF) 2.0M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA **Synchronous Transfer** Up to 600MB/s\* Rate (Maximum)

**Operating Temperature** 

32° to 158° F (0° to 70° C)

**Performance Sequential Read** 540 MB/s\* **Sequential Write** 460 MB/s\* **Random Read** 93K IOPS\*

**Random Write** 74K IOPS\*

**Enterprise Class Features** High Endurance NAND

**Power Loss Protection** 

End-to-End Data Protection

Capacity 960GB



<sup>\*</sup>Actual performance may vary.

<sup>\*</sup>Actual performance may vary.

### **Technical Specifications - Hard Drives**

HP Enterprise Class 960GB SATA SSD Protocol SATA
Form Factor 2.5"
Controller AHCI
NAND Type 3D TLC

**Endurance** 8,760TBW (TB Written)

Reliability (MTTF)2.0M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterface6Gb/s SATASynchronous TransferUp to 600MB/s\*

Rate (Maximum)

**Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 540 MB/s\*

Sequential Write 460 MB/s\*
Random Read 93K IOPS\*
Random Write 74K IOPS\*

**Enterprise Class Features** High Endurance NAND

Power Loss Protection End-to-End Data Protection

<sup>\*</sup>Actual performance may vary.

### **Technical Specifications - Hard Drives**

Performance PCIe SSDs for HP Workstations HP Z Turbo Drive G2 256GB TLC SSD and 256GB SED TLC SSD Capacity256GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLCEndurance200TBReliability (MTBF)1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

Operating Temperature

32° to 158° F (0° to 70° C)

**Performance** 

Sequential Read 3400 MB/s\*
Sequential Write 2500 MB/s\*
Random Read 500K IOPS\*
Random Write 440K IOPS\*

HP Z Turbo Drive G2 512GB TLC SSD and 512GB SED TLC SSD 
 Capacity
 512GB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

 SED Support
 Opal 2

Endurance 300TBW (TB Written)

**Reliability** (MTBF) 1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance Sequential Read** 3500 MB/s\*

Sequential Write 2900 MB/s\*
Random Read 460 K IOPS\*
Random Write 500K IOPS\*

<sup>\*</sup>Actual performance may vary.

<sup>\*</sup>Actual performance may vary.

### **Technical Specifications - Hard Drives**

<b>HP Z Turbo Dri</b>	ve G2
1TB TLC SSD	

Capacity1TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance** Sequential Read 3500 MB/s\*

Sequential Write 3000 MB/s\*
Random Read 580K IOPS\*
Random Write 500K IOPS\*

#### HP Z Turbo Drive G2 2TB TLC SSD

Capacity2TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

**Endurance** 500TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

**Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s\*

Sequential Write 3000 MB/s \*
Random Read 600K IOPS\*
Random Write 500K IOPS\*

<sup>\*</sup>Actual performance may vary.

<sup>\*</sup>Actual performance may vary.

### **Technical Specifications - Hard Drives**

HP	Z	Tu	rbo	Dr	ive	Dua	ıl
Pro	5	12	GB	SSI	D		

**Capacity** 512GB (one M.2 PCIe NVMe module)

**Protocol** PCle

**Form Factor** M.2 in Half-height, half-length card

Controller NVMe NAND Type 3D TLC

**Endurance** 300TBW (TB Written)

**Reliability** (MTBF) 1.5M hours

Interface PCI Express 3.0 x8 electrical x8 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s\*

Sequential Write 2900 MB/s\*
Random Read 460 K IOPS\*
Random Write 500K IOPS\*

#### \*Actual performance may vary.

#### HP Z Turbo Drive Dual Pro 1TB SSD

Capacity 1TB (one M.2 PCIe NVMe module)

Protocol PCI6

**Form Factor** M.2 in Half-height, half-length card

Controller NVMe NAND Type 3D TLC

**Endurance** 400TBW (TB Written)

**Reliability** (MTBF) 1.5M hours

Interface PCI Express 3.0 x8 electrical x8 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s\*

Sequential Write 3000 MB/s\*
Random Read 580K IOPS\*
Random Write 500K IOPS\*

#### \*Actual performance may vary.

#### HP Z Turbo Drive Dual Pro 2TB SSD

Capacity 2TB (one M.2 PCIe NVMe module)

**Protocol** PCIe

**Form Factor** M.2 in Half-height, half-length card

Controller NVMe NAND Type 3D TLC

**Endurance** 500TBW (TB Written)

**Reliability** (MTBF) 1.5M hours

Interface PCI Express 3.0 x8 electrical x8 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance** Sequential Read 3500 MB/s\*

Sequential Write 3000 MB/s \*
Random Read 600K IOPS\*
Random Write 500K IOPS\*



<sup>\*</sup>Actual performance may vary.

### **Technical Specifications - Graphics**

#### **GRAPHICS**

NVIDIA® T400 2GB Graphics **Form Factor** Dimensions: 2.713" H x 6.137" L

Single Slot, Low Profile

Weight: 124g

**Graphics Controller** NVIDIA® T400 Graphics Card

GPU: 384 CUDA cores Power: 30 Watts Cooling: Active

Bus TypePCI Express 3.0 x16MemorySize: 2 GB GDDR6

Memory Interface: 64-bit Memory Bandwidth: 80 GB/s

Connectors 3x mDP

Maximum Resolution 3x 5120 x 2880 x 24 bpp @ 60Hz

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes: CUDA, OpenCL 1.x

**Available Graphics** 

**Drivers** 

Windows 10

Linux

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T400 4GB Graphics Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot, Low Profile

Weight: 124g

**Graphics Controller** NVIDIA® T400 Graphics Card

GPU: 384 CUDA cores Power: 30 Watts Cooling: Active

Bus Type PCI Express 3.0 x16
Memory Size: 4 GB GDDR6

Memory Interface: 64-bit Memory Bandwidth: 80 GB/s

Connectors 3x mDP

**Maximum Resolution** 3x 5120 x 2880 x 24 bpp @ 60Hz

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes: CUDA, OpenCL 1.x



**Technical Specifications - Graphics** 

Available Graphics Drivers Windows 10 Linux

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



### Technical Specifications - Graphics

**NVIDIA® T1000 4GB Graphics** 

**Form Factor** Dimensions: 2.713" H x 6.137" L

> Single Slot Weight: xx

NVIDIA® T1000 Graphics Card **Graphics Controller** 

Power: 50W Cooling: Active

**Bus Type** PCI Express 3.0 x16 Memory Size: 4GB GDDR6

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128-bit

**Connectors** 4x mini DisplayPort™ 1.4a **Maximum Resolution** 7680 x 4320 @ 120Hz

**Display Output** Maximum number of displays: 4 displays

NVIDIA® Turing™ **Architecture** 

**Supported Graphics APIs** 

**Available Graphics** 

**Drivers** 

Microsoft Windows 10

Windows 8.1

Microsoft Windows 7 Professional 64bit

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and

**ARB** extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 8GB Graphics

**Form Factor** Dimensions: 2.713" H x 6.137" L

Single Slot

Weight: 132.6 grams

**Graphics Controller** NVIDIA® T1000 Graphics Card

> Power: 50W Cooling: Active

PCI Express 3.0 x16 **Bus Type** 

Memory Size: 8GB GDDR6

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128-bit

**Connectors** 4x mini DisplayPort™ 1.4a

**Maximum Resolution** 7680 x 4320 @ 120Hz

**Display Output** Maximum number of displays: 4 displays

**Architecture** NVIDIA® Turing™

**Available Graphics** 

**Drivers** 

Windows 11 Windows 10

Windows 8.1

Windows 7 Professional

### **Technical Specifications - Graphics**

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and

**ARB** extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A2000 6GB

Graphics

Form Factor Dimensions: 2.713" H x 6.6" L

Dual slot, half-height

Weight: 295 grams (without extender)

**Graphics Controller** NVIDIA® RTX A2000 Graphics Card

Power: 70W Cooling: Active

**Bus Type** PCI Express 4.0 x16

Memory Size: 6GB GDDR6

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192-bit

**Connectors** 4x mini-DisplayPort™ 1.4a

**Maximum Resolution** Up to 4x 5120 x 2880 x 24bpp @ 60Hz

**Architecture** NVIDIA® Ampere™

Supported Graphics APIs CUDA, OpenCL™ 1.x

**Available Graphics** 

**Drivers** 

Microsoft Windows 11 Microsoft Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

**Notes** 

1. RTX A2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered

separately as AMO:

a. 2MY05AA - HP Single miniDP-to-DP Adapter Cable
b. 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Two mDP-to-DP adapters are included with the RTX A2000 when it is

ordered as an AMO kit.

NVIDIA® RTX A2000 12GB Form Factor

Graphics

Dimensions: 2.713" H x 6.6" L

Dual slot, half-height

Weight: 295 grams (without extender)

**Graphics Controller** NVIDIA® RTX A2000 Graphics Card

Power: 70W Cooling: Active

**Bus Type** PCI Express 4.0 x16

### **Technical Specifications - Graphics**

Memory Size: 12GB GDDR6

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192-bit

**Connectors** 4x mini-DisplayPort™ 1.4a

Maximum Resolution Up to 4x 5120 x 2880 x 24bpp @ 60Hz

**Architecture** NVIDIA® Ampere™

Supported Graphics APIs CUDA, OpenCL™ 1.x

**Available Graphics** 

**Drivers** 

Microsoft Windows 11 Microsoft Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

**Notes** 

 RTX A2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately as AMO:

a. 2MY05AA - HP Single miniDP-to-DP Adapter Cable
 b. 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Two mDP-to-DP adapters are included with the RTX A2000 when it is ordered as an AMO kit.

#### NVIDIA® Quadro® RTX 4000 8GB Graphics

**Form Factor** 

Full-Height Single Slot (4.4" Height x 9.5" Length)

Weight: 550 grams / 1.21 lbs

Graphics Controller

NVIDIA® Quadro® RTX 4000 Graphics

GPU: 2304 NVIDIA® CUDA® Parallel Processing Cores Power: 160 Watts (125W graphics + 35W USB-C® PD)

Cooling: Active

Memory 8GB GDDR6

Memory Bandwidth: Up to 416 GB/s

Memory Width: 256-bit

**Connectors** 3x DisplayPort<sup>™</sup> 1.4 and 1x VirtualLink

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DisplayPort<sup>™</sup> to VGA, DisplayPort<sup>™</sup> to DVI, and DisplayPort<sup>™</sup> to Dual-Link

DVI adapters available as accessories.

### **Technical Specifications - Graphics**

**Maximum Resolution** DisplayPort™ 1.4:

- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution<sup>2</sup>

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz- up to 4x 3840 x 2160 x 24 bpp @ 120Hz

- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz

**Image Quality Features** Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort™, and HDMI connectors NVIDIA® 3D Vision™ and other 3D stereo technologies

NVIDIA® Mosaic and nView

**Display Outputs**<sup>1</sup> Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

**Supported Graphics APIs** DirectX°12, OpenGL° 4.6, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran

**Available Graphics** 

**Drivers** 

Windows® 10 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

**Notes** 1- Supports up to a total of 4 displays

2- Display must be capable of DSC or 2-cabled solution to obtain

this resolution

NVIDIA® RTX A4000 16GB Graphics Form Factor

Full-Height Single Slot (4.4" Height x 9.5" Length)

**Graphics Controller** NVIDIA® RTX A4000 Graphics

GPU: 6144 NVIDIA® CUDA® Parallel Processing Cores

Power: 140 Watts Cooling: Active

Memory 16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

**Connectors** 4x DP

One 6-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

**Technical Specifications - Graphics** 

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

**Display Outputs**<sup>1</sup> 4x DP

**Supported Graphics** 

**APIs** 

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

**Available Graphics** 

**Drivers** 

Windows® 10 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A4500 20GB Graphics **Form Factor** 

Full-Height Dual Slot (4.4" Height x 10.5" Length)

**Graphics Controller** 

**NVIDIA® RTX A4500 Graphics** 

GPU: 7168 NVIDIA® CUDA® Parallel Processing Cores

Power: 200 Watts Cooling: Active

Memory 20GB GDDR6 memory

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

Connectors

4x DP

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

**Display Outputs**<sup>1</sup> 4x DP

**Supported Graphics** 

**APIs** 

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

#### Technical Specifications - Graphics

Available Graphics
Drivers

Windows 11 Windows 10 Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® Quadro® RTX 5000 16GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 975 grams + 75 grams extender

**Graphics Controller** NVIDIA® QUADRO® RTX 5000

GPU: 3072 CUDA cores, 384 Tensor Cores, 48 RT Cores Power: 265 Watts (230W graphics + 35W USB-C® PD)

Cooling: Active

Memory 16GB GDDR6

Memory Bandwidth: Up to 448 GB/s ECC Memory (disabled by default)

**Connectors** 4x DisplayPort™ 1.4 with HDR support and 1x VirtualLink

1x 8-pin and 1x 6-pin auxiliary power connectors

1x NVLink

Quadro Sync connector (compatible with Quadro II Sync)

3-pin mini-DIN connector via optional bracket

4-pin header for stereo signal

After market option Kit: no power adapter included with card.

DisplayPort<sup>™</sup> to VGA, DisplayPort<sup>™</sup> to DVI (single-link and dual-link), and

DisplayPort<sup>™</sup> to HDMI adapters available as accessories.

**Maximum Resolution** DisplayPort™ 1.4:

- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution<sup>2</sup>

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz- up to 4x 4096 x 2160 x 24 bpp @ 120Hz

- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz

**Image Quality Features** HDR support over DisplayPort™ 1.4 (SMPTE 2084/2086, BT.

2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b

**HEVC Encode**)

HDCP 2.2 support over DisplayPort™ and HDMI connectors

NVIDIA 3D Vision™ technology

NVIDIA Mosaic and nView Desktop Management

**Display Outputs** Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

### **Technical Specifications - Graphics**

GPU Architecture NVIDIA® Turing

Supported Graphics APIs DirectX®12, OpenGL® 4.6

Developer API support includes: CUDA C, CUDA C++, DirectCompute,

OpenCL™, Java, Python, and Fortran

**Available Graphics** 

**Drivers** 

Windows® 10 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included

After market option kit: No adapters included

NVIDIA® RTX A5000 24GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

**Graphics Controller** NVIDIA® RTX A5000

GPU: 8192 CUDA Cores

Power: 230W Cooling: Active

Memory 24GB GDDR6

Memory Bandwidth: Up to 768GB/s ECC Memory (disabled by default)

**Connectors** DP (x4) with HDR support

One 8-pin auxiliary power connector

After market option Kit: no power adapter included with card.

DisplayPort<sup>™</sup> to VGA, DisplayPort<sup>™</sup> to DVI (single-link and dual-link), and DisplayPort<sup>™</sup> to HDMI adapters available as accessories.

**Maximum Resolution** DisplayPort™ 1.4a:

7680x4320 @ 120Hz

**Display Outputs** 4x DP1.4a HDR2 outputs (up to 7680x4320 @ 120Hz)

**GPU Architecture** NVIDIA® Ampere™

Supported Graphics

APIs

DirectX®12, OpenGL® 4.5

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

**Technical Specifications - Graphics** 

Available Graphics Drivers

Windows® 10 64-bit Windows® 7 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters

included

After market option kit: No adapters included



### **Technical Specifications - Graphics**

NVIDIA® RTX™ A6000 48GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

**Graphics Controller** NVIDIA® RTX™ A6000 Graphics

GPU: 10752 NVIDIA® CUDA® Parallel Processing Cores

Power: 300 Watts Cooling: Active

Memory 48GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

**Connectors** 4x DP 1.4a

Quadro Sync II connector

Ampere NVLink® Stereo Sync

Requires 8-pin CPU auxiliary power

**Maximum Resolution** 5120x2880 @ 60Hz (up to 4 displays)

**Display Outputs** 4x DP 1.4 (7680x4320 @ 60Hz)

Supported Graphics APIs DirectX°12, OpenGL° 4.6, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran™

**Available Graphics** 

**Drivers** 

Windows® 10 64-bit

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



### Technical Specifications - Networking and Communications

#### **NETWORKING AND COMMUNICATIONS**

Integrated Intel I219 PCIe Connector **GbE Controller** 

Controller Intel I219 GbE platform LAN connect networking controller

**Data Rates Supported** 10/100/1000 Mbps **Boot ROM Support** PXE, UEFI, iSCSI Boot Link/Activity LED **Connect Speed LED Indicators** 

Off = No link Blinking = Activity

Speed LED

**RJ-45** 

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Wake-On-LAN, Intel® Active Management Technology™ (AMT) 11.12

Integrated Marvell AQC- Connector 107

**RJ-45** 

**Controller** Marvell AQtion AQC-107

**Data Rates Supported** 10/100/1000 Mbps, 2.5/5/10 Gbps

**Boot ROM Support** PXE. UEFI **Connect Speed LED** Link/Activity LED

**Indicators** Off = No link Blinking = Activity

Speed LED

Amber = < 10 Gbps

Green = 10Gbps

Management Capabilities Wake-On-LAN

Intel® I210-T1

**Networking Interface RJ-45** 

**System Interface** PCI Express 2.1 x1

**Networking Speeds** 

Cabling (up to 100m)

Supported

10Mbps, 100Mbps, 1Gbps

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps

**Power Consumption** (active-typical)

0.81W

**Physical Dimensions** 

Length: 6.7cm (2.64 inches)

(Bracket) Width: 1.8cm (0.709 inches)

Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)

### Technical Specifications - Networking and Communications

**Connect Speed LED Indicators** 

Link/Activity LED

- Off = No link
- Blinking = Activity

Speed LED

- Off = 10Mbps
- Green = 100Mbps
- Amber = 1Gbps

**Operating Temperature** 

**Hardware Certifications** 

0 °C to 55 °C (32 °F to 131 °F)

USA: FCC B, EU: UL CE,

Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

2 x RJ-45

Canada: ICES-003/NMB-003

Intel® X550-T2

**Networking Interface** 

**System Interface** 

PCI Express 3 x4

**Networking Speeds** 

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps

Cabling (up to 100m)

Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6a (or higher) for 10Gbps

**Power Consumption** 

(active-typical)

3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps

**Physical Dimensions** 

**Connect Speed LED** 

**Indicators** 

5.2 in x 2.7 in (without bracket) Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = No link

Amber = <10Gbps

Green = 10Gbps

**Operating Temperature** 

0 °C to 55 °C (32 °F to 131 °F)

**Hardware Certifications** 

USA: FCC B. EU: UL CE, Japan: VCCI,

Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

### Technical Specifications - Networking and Communications

Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC **Networking Interface** 1Gb LC Fiber 850 nm

**System Interface** PCIeG2 x1, Half Height, Half Length

**Networking Speeds Supported** 1000Base-X (1Gbps)

**Cabling** 50/125 μm (core/cladding) multimode fiber optic cable

up to 500m

62.5/125 µm (core/cladding) multimode fiber optic cable

up to 220m

**Power Consumption (active-typical)** 1.5 Watts

Physical Dimensions8.8 cm x 6.9 cm (3.5 in x 2.7 in)Connect Speed LED IndicatorsON: 1Gbps Link OFF: Link downOperating Temperature-25°C to 70°C (-13°F to 158°F)

**Hardware Certifications** IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs),

IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X),

IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-

TICK, VCCI



Date of change:	Version History:		Description of change:
December 17, 2020	From v1 to v2	Changed	Storage / Hard Drives and Graphics sections
February 1, 2021	From v2 to v3	Changed	Processors and NETWORKING AND COMMUNICATIONS sections
March 1, 2021	From v3 to v4	Changed	Overview and Other Hardware sections
April 13, 2021	From v4 to v5	Changed	Racking and Physical Security sections
April 21, 2021	From v5 to v6	Changed	Format page 2 and 3
June 1, 2021	From v6 to v7	Changed	Graphics section
September 1, 2021	From v7 to v8	Changed	Graphics section
December 3, 2021	From v8 to v9	Changed	SOFTWARE AND SECURITY section
February 1, 2022	From v9 to v10	Changed	Operating Systems, Graphics, Application Software and Input
			Devices sections
March 1, 2022	From v10 to v11	Changed	Social and Environmental Responsibility section
April 1, 2022	From v11 to v12	Changed	Graphics section
May 2, 2022	From v12 to v13	Changed	Format page 7
June 1, 2022	From v13 to v14	Changed	Graphics section
July 1, 2022	From v14 to v15	Changed	Networking and Communications section

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